

**AMENDMENT TRANSMITTAL LETTER**Docket No.  
SON-1745Application No.  
09/512,336-Conf. #5387Filing Date  
February 24, 2000Examiner  
K. ChenArt Unit  
1765

Applicant(s): Seichi Fukuda

Invention: DRY ETCHING METHOD AND METHOD OF MANUFACTURING SEMICONDUCTOR APPARATUS

**TO THE COMMISSIONER FOR PATENTS**

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

**CLAIMS AS AMENDED**

	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	4	- 20 =		x	0.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:</b>					0.00

☒ Large Entity☐ Small Entity☒ No additional fee is required for this amendment.☐ Please charge Deposit Account No. \_\_\_\_\_ in the amount of \$ \_\_\_\_\_.  
A duplicate copy of this sheet is enclosed.☐ A check in the amount of \$ \_\_\_\_\_ to cover the filing fee is enclosed.☐ Payment by credit card. Form PTO-2038 is attached.☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 18-0013  
as described below. A duplicate copy of this sheet is enclosed.☒ Credit any overpayment.☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.Dated: May 14, 2003Ronald P. Kananen Reg. 24,104  
David K. Benson Reg. 42,314RADER, FISHMAN & GRAUER PLLC  
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Suite 501  
Washington, DC 20036  
(202) 955-3750RECEIVED  
MAY 15 2003  
TC 1700 MAIL ROOM



Docket No.: SON-1745  
(PATENT)

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5/15/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Seiichi Fukuda

Application No.: 09/512,336

Group Art Unit: 1765

Filed: February 24, 2000

Examiner: K. Chen

For: DRY ETCHING METHOD AND METHOD OF  
MANUFACTURING SEMICONDUCTOR  
APPARATUS

RECEIVED  
MAY 15 2003  
TC 1700 MAIL ROOM

AMENDMENT

**Box Non-Fee Amendment**  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated February 14, 2003 (Paper No. 21), please  
amend the above-identified U.S. patent application as follows: